

CNM Short Course A: Fundamentals of High Aspect Ratio Pattern Transfer by Deep Reactive Ion Etching (DRIE) Processes

Time: 8:30 – 12:00

Date: Thursday, April 23

Location: Building 440, Room A105

Instructors: Ralu Divan and Thomas Cecil

Lecturer: Dr. Pratik Kothary (PlasmaTherm)

Description: This course will discuss and demonstrate pattern transfer by dry etch DRIE. The applications of these processes are the transfer of 2D patterns in thin films and substrates and the micro- and nanofabrication of 3D structures in substrates. This course will also present new complementary technologies such as Fast Atomic Sequential Technology (FAST) and stripping and cleaning technologies.

Max Attendees: 10

Note: Attendees can bring samples. Scanning Electron Microscopy (SEM) will be done for etched samples upon request.